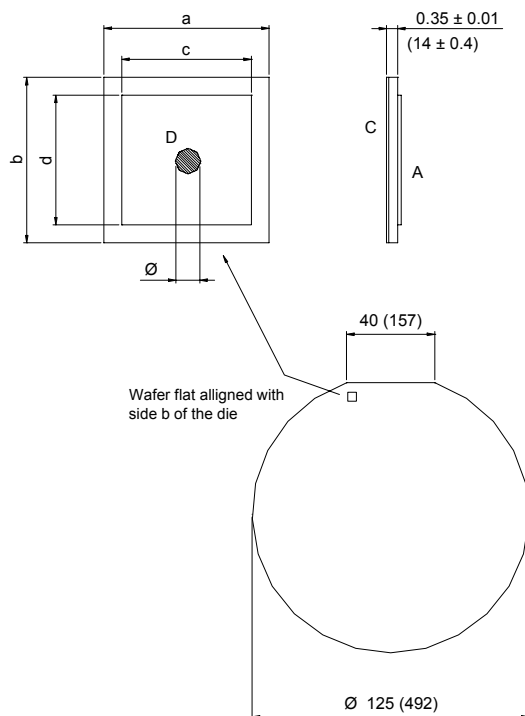


SCHOTTKY DIE 95 x 95 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (MILS).
2. CONTROLLING DIMENSION: (MILS).
3. DIMENSIONS AND TOLERANCES:
 - $a = 2.41 \pm 0.01$
(95 $\pm$ 0, - 0.4)
 - $b = 2.41 \pm 0.01$
(95 $\pm$ 0, - 0.4)
 - $c = 2.26 \pm 0.01$
(89 $\pm$ 0, - 0.4)
 - $d = 2.26 \pm 0.01$
(89 $\pm$ 0, - 0.4)
 - $\varnothing = 1 \pm 0.15$
(40 $\pm$ 6)
4. LETTER DESIGNATION:
 - A = Anode (Top Metal)
 - C = Cathode (Back Metal)
 - D = Reject Ink Dot (only on non-conforming dies)
5. SAWING:
 - Recommended Blade
 - SEMITEC S1025 QS00 Blade
 - Sawing Street
 - 0.05 ± 0.005
 - (2 $\pm$ 0, - 0.2)

NOT TO SCALE

NOTE: 10 mils die thickness is available on specific request only.
Contact factory for information.

Electrical Characteristics

Device #	T _J Max. (°C)	V _R (V)	Typ. I _R @ 25°C (μA)	Typ. I _R @ 125°C (mA)	Max. V _F @ I _F (V)	Package Style
SC095R015x5x	125	15	n.a. contact factory			
SC095S020x5x	150	20	n.a. contact factory			
SC095S030x5x	150	30	n.a. contact factory			
SC095S045x5x	150	45	n.a. contact factory			
SC095S060x5x	150	60	n.a. contact factory			
SC095H045x5x	175	45	15	5	0.84 @ 20A	TO-220
SC095H100x5x	175	100	n.a. contact factory			
SC095H150x5x	175	150	n.a. contact factory			

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC095xxxxA5x	Wire Bondable	—	Al 30 kÅ	—	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC095xxxxS5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

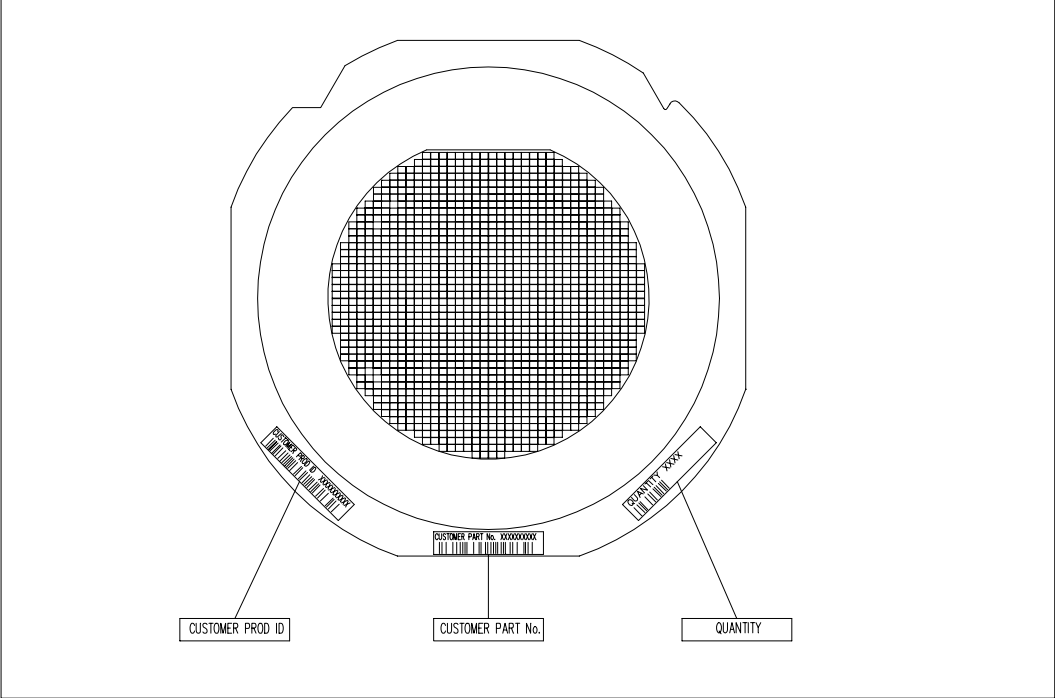
Device #	Description	Minimum Order Quantity Die in Sale Package
SC095xxxxx5B	Inked Probed Unsawn Wafer (Wafer in Box)	1545
SC095xxxxx5R	Probed Die in Tape & Reel	n. a.
SC095xxxxx5P	Probed Die in Waffle Pack	1545
SC095xxxxx5F	Inked Probed Sawn Wafer on Film	1545

Ordering Information Table

Device Code						
SC	095	H	150	A	5	B
1	2	3	4	5	6	7
1	- Schottky Die					
2	- Chip Dimension in Mils					
3	- Process (see Electrical Characteristics Table)					
4	- Voltage code: Code = V_{RRM}					
5	- Chip surface metallization (see Mechanical Data Table)					
6	- Wafer Diameter in inches					
7	- Packaging (see Packaging Table)					

H = 830 Process
R = OR'ing Process
S = Standard Process

Wafer on Film

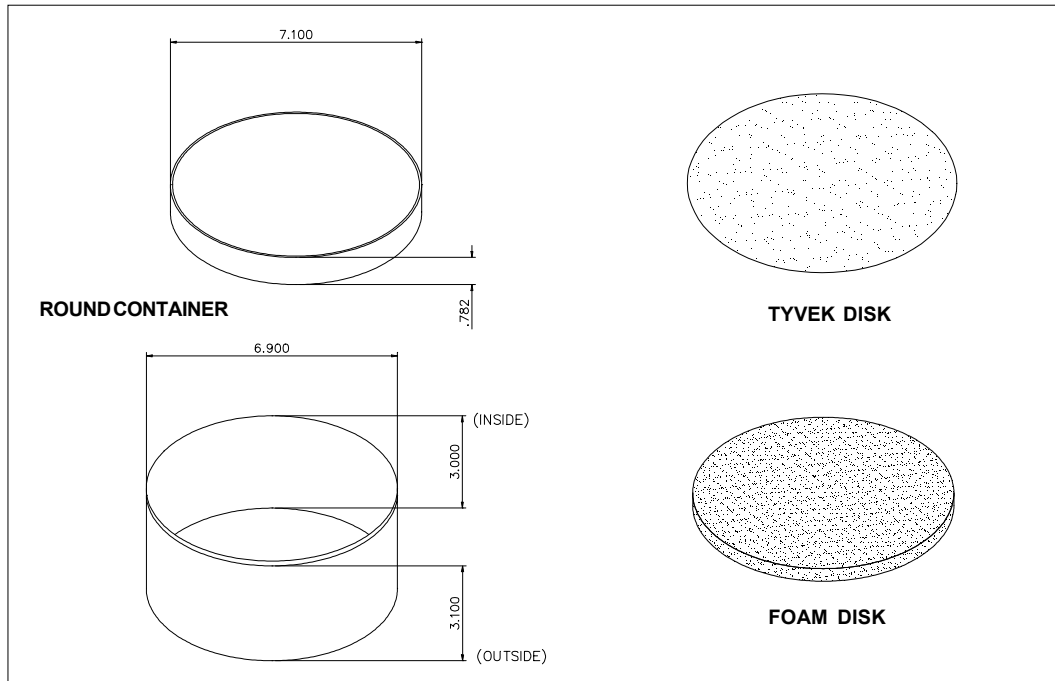


SC095.....5.

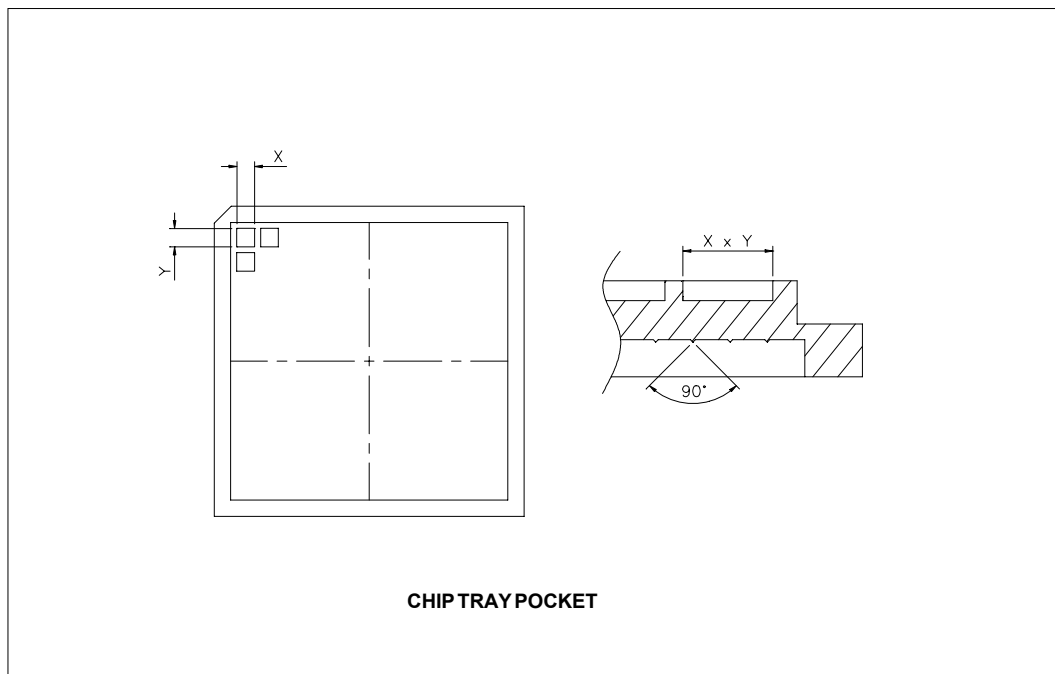
Bulletin 10500J rev.A 05/01

International
IR Rectifier

Wafer in Box



Die in Waffle Pack



WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245 U.S.A. Tel: (310) 322 3331. Fax: (310) 322 3332.
EUROPEAN HEADQUARTERS: Hurst Green, Oxted, Surrey RH8 9BB, U.K. Tel: ++ 44 1883 732020. Fax: ++ 44 1883 733408.
IR CANADA: 15 Lincoln Court, Brampton, Markham, Ontario L6T3Z2. Tel: (905) 453 2200. Fax: (905) 475 8801.
IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg. Tel: ++ 49 6172 96590. Fax: ++ 49 6172 965933.
IR ITALY: Via Liguria 49, 10071 Borgaro, Torino. Tel: ++ 39 11 4510111. Fax: ++ 39 11 4510220.
IR FAR EAST: K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo, Japan 171. Tel: 81 3 3983 0086.
IR SOUTHEAST ASIA: 1 Kim Seng Promenade, Great World City West Tower, 13-11, Singapore 237994. Tel: ++ 65 838 4630.
IR TAIWAN: 16 Fl. Suite D.207, Sec. 2, Tun Haw South Road, Taipei, 10673, Taiwan. Tel: 886 2 2377 9936.

<http://www.irf.com>

Fax-On-Demand: +44 1883 733420

Data and specifications subject to change without notice.